

Physics-Based Prediction of Interlayer Delamination Initiation and Propagation

Students: Weidong Xie, Shahsi Hegde

Faculty: Suresh Sitaraman

OBJECTIVES:

- Establish a framework for thermo-mechanical evaluation of interfacial integrity in multilayered structures
- Create a model for interfacial stress analysis for unsymmetric, anisotropic multilayered structures
- Develop an innovative technique for measuring the critical free-edge Stress-Intensity Factor
- Develop a test method for calibrating the interfacial fracture resistance
- Investigate interfacial delamination under monotonic and cyclic loading
- Develop models for predicting fatigue life of interfacial cracks
- Develop design guidelines, base substrate material properties, interlayer dielectric material properties to enhance interfacial integrity

APPROACH

1. Develop Models for Interfacial Stress Estimation:

- Identify potential failure sites
- Reduce design window
- Select suitable materials
- Stress control in reliability design
- Optimum design

3. Delamination Propagation Models:

- Predict possible failure during process.
- Calibrate interfacial fracture resistance.
- Study delamination under thermal cycling

2. Predict Delamination onset

- Identify ability against delamination initiation
- Design against interlayer debonding

4. Interface Integrity of SOP

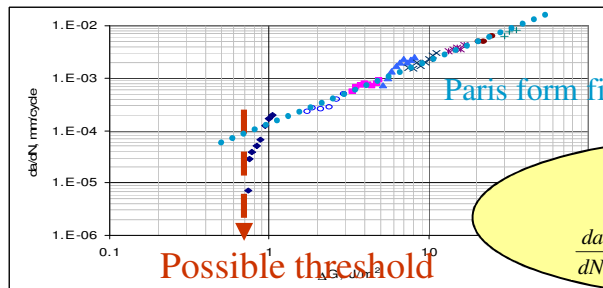
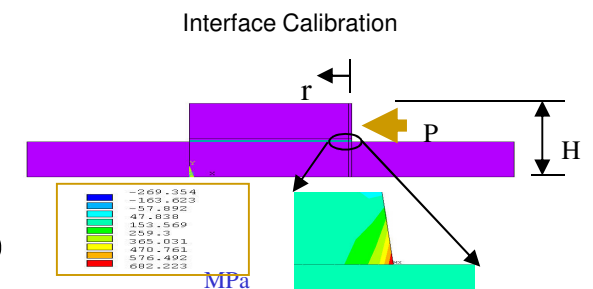
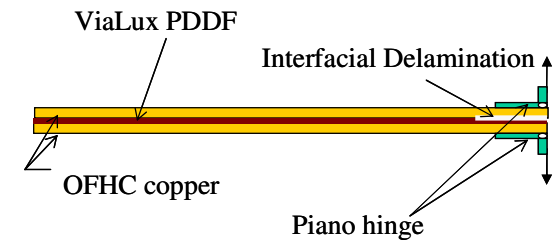
- Use the developed modeling methodology for thermo-mechanical reliability assessment and interfacial integrity of SOP substrates
- Validated the methodology using test vehicles

ACCOMPLISHMENTS:

- Created a model for interfacial stress analysis for unsymmetric, anisotropic multilayered
- Developed an innovative technique for measuring the critical free-edge Stress-Intensity Factor.
- Developed a test method for calibrating the interfacial fracture resistance.
- Performed design of simulations for SOP substrate



Fatigue crack propagation



Paris equation

$$\frac{da}{dN} = 1.14286 \times 10^{-4} (\Delta G)^{1.1902}$$